

General Description

The WSP9936 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP9936 meet the RoHS and Green Product requirement with full function reliability approved.

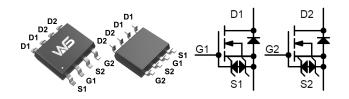
Product Summery

BVDSS	RDSON	ID
20V	14mΩ	8A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:2KV

SOP-8 Pin Configuration



Advanced high cell density Trench technologySuper Low Gate Charge

Features

- Excellent Cdv/dt effect decline
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	20	V	
V _{GS}	Gate-Source Voltage	±12	V	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	А		
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	6.1	А	
I _{DM}	Pulsed Drain Current ² 40		A	
P _D @T _A =25℃	Total Power Dissipation ³ 2		W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹		62.5	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		10	°C/W



Dual N-Channel MOSFET

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.022		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =8A		15	26	-mΩ
R _{DS(ON)}		V _{GS} =2.5V , I _D =6.8A		19	34	
V _{GS(th)}	Gate Threshold Voltage		0.5	0.75	1.1	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_{D}=250$ uA		-2.33		mV/℃
	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}16V$, $V_{\text{GS}}\text{=}0V$, $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			1	uA
I _{DSS}		V_{DS} =16V , V_{GS} =0V , T _J =55 $^{\circ}$ C			5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		25		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		4.5		Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =10V , V _{GS} =4.5V , I _D =8A		15.6	17	
Q _{gs}	Gate-Source Charge			1.3		nC
Q _{gd}	Gate-Drain Charge			2.5		
T _{d(on)}	Turn-On Delay Time	V_{DD} =10V, V_{GS} =4.5V, R_G =6 Ω		4	9.5	
Tr	Rise Time			6	24	ns
T _{d(off)}	Turn-Off Delay Time			25	73	
T _f	Fall Time			4	39	
Ciss	Input Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		520		
C _{oss}	Output Capacitance			105		pF
C _{rss}	Reverse Transfer Capacitance			60		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}				3.7	А
I _{SM}	Pulsed Source Current ^{2,4}	$V_G = V_D = 0V$, Force Current			40	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time			19.2		nS
Qrr	Reverse Recovery Charge	IF=8A , dl/dt=100A/ μs , T _J =25 $^{\circ}$ C		4.6		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

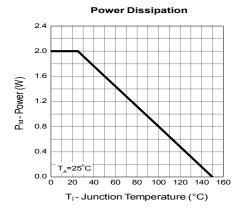
2.The data tested by pulsed , pulse width $\leq 300us$, duty cycle $\leq 2\%$ 3.The power dissipation is limited by 150 $^\circ\!C\,$ junction temperature

4. The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

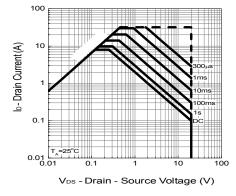


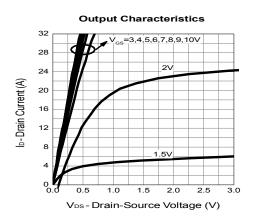
Dual N-Channel MOSFET

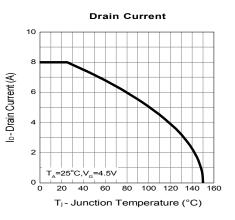
Typical Characteristics



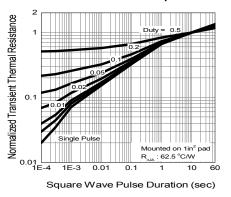
Safe Operation Area







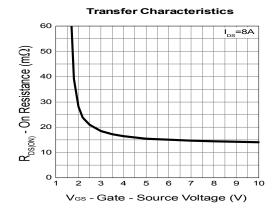
Thermal Transient Impedance

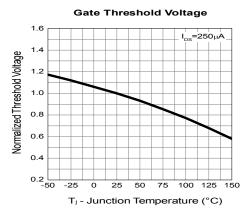


Drain-Source On Resistance 36 32 Ros(ov) - On - Resistance (mΩ) 28 24 =2.5 20 4.5 16 12 8 4 ∟ 0 10 15 20 25 30 5 ID - Drain Current (A)

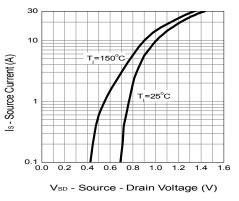


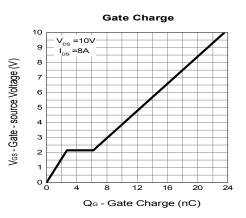
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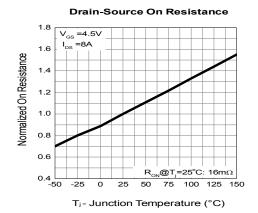


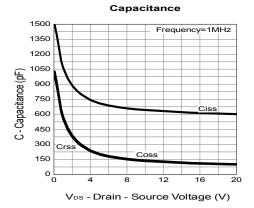


Source-Drain Diode Forward











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